



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Kinsman et. al

**Serial No.:** 10/648,654

**Filed:** August 26, 2003

**For:** METHODS FOR STRESS  
REDUCTION FEATURE FOR LOC LEAD  
FRAME

**Confirmation No.:** 3870

**Examiner:** J. Fischer

**Group Art Unit:** 1733

**Attorney Docket No.:** 2269-2739.6US  
(95-1011.05/US)

**Notice of Allowance Mailed:**

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P.O. Box 1450  
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Sir:

Please amend the above-referenced application as follows:

**Amendments to the Title** begin on page 3 of this paper;

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

**Amendments to the Specification** begin on page 4 of this paper;

**Amendments to the Claims** are set forth in the listing of the claims that begins on page 7 of this paper;

**Corrections to the Drawings** are summarized on page 17 of this paper, with a replacement sheet and an annotated sheet showing the corrections enclosed herewith; and

**Remarks** start at page 18 of this paper.

**IN THE TITLE:**

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**METHODS-ASSEMBLY METHOD FOR SEMICONDUCTOR DIE AND STRESS REDUCTION FEATURE FOR LOC LEAD FRAME**